Part Number:	AH173-WG-7-A AH173-WG-7-B AH175-WG-7-A AH175-WG-7-B
Weight (mg):	14.08

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.2763	0.6021	1000000	42763
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	36.1570	5.0909	992600	358894
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	976
		Sn	7440-31-5	0.25%			2500	904
		Zn	7440-66-6	0.22%			2200	795
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.8878	0.125	1000000	8878
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.4233	0.0596	1000000	4233
Encapsulation	EME-G600	Epoxy Resin	------	5.00%	56.8075	7.9985	50000	28404
		Phenol Resin	------	5.00%			50000	28404
		Bismuth/Bismuth compound	------	1.00%			10000	5681
		SiO2	60676-86-0	86.50%			865000	491385
		Cresol Novolac	29690-82-2	2.00%			20000	11362
		C	1333-86-4	0.50%			5000	2840
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	0.7358	0.1036	750000	5518
		epoxy resin	Trade secret	20.00%			200000	1472
		curing agent & hardener	Trade secret	5.00%			50000	368
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.7124	0.1003	1000000	7124
				Total	100.00	14.08		1000000

Tolerance ±10%

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* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS **and** reported above:

Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number:	AH173-WL-7-A AH173-WL-7-B AH175-WL-7-A AH175-WL-7-B							
Weight (mg):	14.08							
Element	**Material Group**	**Materials**	**CAS (if applicable)**	**Average mass homogeneous Materal(%)**	**Percent of whole (%)**	**Mass (mg)**	**ppm Homogeneous Material**	**ppm overall**
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.2763	0.6021	1000000	42763
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	36.1570	5.0909	992600	358894
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	976
		Sn	7440-31-5	0.25%			2500	904
		Zn	7440-66-6	0.22%			2200	795
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.8878	0.125	1000000	8878
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.4233	0.0596	1000000	4233
Encapsulation	EME-6600CSP	SiO2	60676-86-0	77.20%	56.8075	7.9985	772000	438554
		Epoxy Resin	------	10.00%			100000	56808
		Bismuch/Bismuch compound	------	1.00%			10000	5681
		Phenol Novolac	9003-35-4	5.00%			50000	28404
		Antimony trioxide	1309-64-4	3.00%			30000	17042
		Brominated epoxy resin	68541-56-0	3.50%			35000	19883
		C	1333-86-4	0.30%			3000	1704
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	0.7358	0.1036	750000	5518
		epoxy resin	Trade secret	20.00%			200000	1472
		curing agent & hardener	Trade secret	5.00%			50000	368
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.7124	0.1003	1000000	7124
				Total	100.00	14.08		1000000

Tolerance ±10%

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Asbestos
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: AH173-PL-A-A AH173-PL-A-B AH173-PL-B-A AH173-PL-B-B AH175-PL-A-A AH175-PL-A-B AH175-PL-B-A AH175-PL-B-B

Weight (mg): 101.71

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.5920	0.6021	1000000	5920
Leadframe	SIP-3/PMC90	Cu	7740-50-8	99.77%	67.7894	68.95	997700	676335
		Ag	7740-22-4	0.10%			1000	678
		Fe	7439-89-6	0.10%			1000	678
		P	7723-14-0	0.03%			300	203
Epoxy Adhesive	AG-03X7	Silver Flake	7440-22-4	71.25%	0.2065	0.21	712500	1471
		Epoxy resin	25068-38-6	9.50%			95000	196
		Solvent	96-48-0	9.00%			90000	186
		Hardener	25550-51-0	9.50%			95000	196
		Accelarator	Trade Secret	0.75%			7500	15
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.0295	0.03	1000000	295
Encapsulation	EME-6300H	Silicon Fused	60676-86-0	70%	26.2211	26.67	700000	183547
		Epoxy	29690-82-2	20%			200000	52442
		Phenol novolac	9003-35-4	7.50%			75000	19666
		Antimony Trioxide	1309-64-4	2.50%			25000	6555
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	5.1616	5.25	1000000	51616
				Total	100.00	101.71		1000000

Tolerance ±10%

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Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

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4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate